

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

Claims 1-43 (canceled)

44. (currently amended) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has having a front surface facing said top surface of said substrate and a back surface opposite to said front surface, and wherein said front surface semiconductor chip comprises multiple pads at said front surface; ~~wherein said front surface is on the bottom of said semiconductor chip, and wherein said back surface of said semiconductor chip is on the top of said semiconductor chip;~~

an identity of product ~~a machine readable information directly on said back surface of said semiconductor chip;~~ ~~wherein said machine readable information is an identity of product and manufacturer or said machine readable information is a bar code;~~

multiple metal bumps ~~directly on~~ between said multiple pads of said semiconductor chip and said top surface of said substrate; ~~wherein said multiple metal bumps attach said semiconductor chip to a top surface of said substrate; and~~

an optically transparent layer directly over ~~said back surface, wherein said optically transparent layer covers~~ said identity of product and manufacturer or said bar code, wherein said identity of product and manufacturer or said bar code is visible and machine readable through said optically transparent layer.

Claims 45-47 (canceled)

48. (previously presented) The circuit component of claim 44 further comprising an underfill between said front surface and said top surface of said substrate, wherein said underfill encloses said multiple metal bumps.

49. (previously presented) The circuit component of claim 44 further comprising multiple balls on a bottom surface of said substrate.

Claims 50-59 (canceled)

60. (previously presented) The circuit component of claim 44, wherein said multiple metal bumps comprise solder.

61. (new) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has a front surface facing said top surface of said substrate and a back surface opposite to

said front surface, and wherein said semiconductor chip comprises multiple pads at said front surface;

an identity of manufacturer directly on said back surface of said semiconductor chip;

multiple metal bumps between said multiple pads of said semiconductor chip and said top surface of said substrate; and

an optically transparent layer directly over said identity of manufacturer, wherein said identity of manufacturer is visible through said optically transparent layer.

62. (new) The circuit component of claim 61 further comprising an underfill between said front surface and said top surface of said substrate, wherein said underfill encloses said multiple metal bumps.

63. (new) The circuit component of claim 61 further comprising multiple balls on a bottom surface of said substrate.

64. (new) The circuit component of claim 61, wherein said multiple metal bumps comprise solder.

65. (new) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has a front surface facing said top surface of said substrate and a back surface opposite to

said front surface, and wherein said semiconductor chip comprises multiple pads at said front surface;

a bar code directly on said back surface of said semiconductor chip;

multiple metal bumps between said multiple pads of said semiconductor chip and said top surface of said substrate; and

an optically transparent layer directly over said bar code, wherein said bar code is visible through said optically transparent layer.

66. (new) The circuit component of claim 65 further comprising an underfill between said front surface and said top surface of said substrate, wherein said underfill encloses said multiple metal bumps.

67. (new) The circuit component of claim 65 further comprising multiple balls on a bottom surface of said substrate.

68. (new) The circuit component of claim 65, wherein said multiple metal bumps comprise solder.